

What is claimed is:

1. A semiconductor integrated circuit device comprising:

5 a predetermined I/O cells provided in an I/O area in a peripheral portion of a chip and to be connected to external pins;

signal wirings which transfer a test signal to said I/O cells and are provided in said I/O area in a layout direction of said plurality of I/O cells; and

10 at least one empty cell where said signal wirings run and which is to be a transfer path for said test signal, is provided in said I/O area and has a repeater circuit that receives said test signal and outputs said test signal.

2. The semiconductor integrated circuit device
15 according to claim 1, wherein an optimal repeater circuit having a characteristic which satisfies a delay condition for at least a predetermined signal is selected from plural types of repeater circuits different from one another in electric characteristics previously prepared for one empty
20 cell or a plurality of empty cells in said I/O area and is laid out in said one empty cell or said plurality of empty cells as said repeater circuit for said empty cell.

3. The semiconductor integrated circuit device
according to claim 1, wherein said I/O cells include a
25 boundary-scan register circuit and said signal wirings include a wiring for a signal to be supplied to said boundary-scan register circuit.

4. The semiconductor integrated circuit device

according to claim 3, wherein said I/O cells include a scan flip-flop circuit for a scan path test and said signal wirings include a wiring for a scan path test signal to be supplied to said scan flip-flop circuit.

5 5. A design automation apparatus for a semiconductor integrated circuit, comprising:

 a memory unit which stores I/O cell layout position information, I/O cell size information, I/O cell test terminal information, technology information including
10 design information, and information on a repeater circuit to be laid out in an empty cell for each type of I/O cells on a chip which are to be connected to external pins;

 a computing section which computes a wiring length of a sub net between adjoining I/O cells for test signals
15 (called "test net") to be connected to an area for layout of I/O cells (called "I/O area") at a peripheral portion of a chip by referring to said I/O cell layout position information, I/O cell size information and I/O cell test terminal information in said memory unit and outputs said
20 wiring length;

 a circuit simulator;

 a determining section which computes information at least on a wiring resistance and a capacitance for said sub net, causes said circuit simulator to execute circuit
25 simulation to acquire a wiring delay of said sub net and waveform depression at an end of said sub net, and determines an optimal repeater circuit to be inserted in an empty cell where said sub net passes, based on said

information on said repeater circuit stored in said memory unit in case where said wiring delay and waveform depression concerning said sub net are out of a predetermined range of allowance defined in said technology information; and

5 a layout section which lays out an empty cell including said determined repeater circuit in said I/O area.

6. The design automation apparatus according to claim 5, wherein said determining section which determines a repeater circuit includes a control section which executes a circuit simulation for a sub net divided by insertion of a
10 selected repeater circuit to acquire a wiring delay and waveform depression concerning said divided sub net, determines whether said wiring delay and waveform depression concerning said divided sub net fall within said range of
15 allowance defined in said technology information or not, and searches for an optimal repeater circuit by selecting another repeater circuit or further dividing said sub net in case where said wiring delay and waveform depression do not fall within said range of allowance.

20 7. A design automation method for a semiconductor integrated circuit using a computer having a memory unit which stores I/O cell layout position information, I/O cell size information, I/O cell test terminal information, technology information including design information, and
25 information on a repeater circuit to be laid out in an empty cell for each type of I/O cells on a chip which are to be connected to external pins, said method comprising the steps of:

computing a wiring length of a sub net between
adjoining I/O cells for test signals (called "test net") to
be connected to an area for layout of I/O cells (called "I/O
area") at a peripheral portion of a chip by referring to
5 said I/O cell layout position information, I/O cell size
information and I/O cell test terminal information in said
memory unit and outputting said wiring length;

computing information at least on a wiring resistance
and a capacitance for said sub net, causing said circuit
10 simulator to execute circuit simulation to acquire a wiring
delay of said sub net and waveform depression at an end of
said sub net;

determining an optimal repeater circuit to be inserted
in an empty cell where said sub net passes, based on said
15 information on said repeater circuit stored in said memory
unit in case where said wiring delay and waveform depression
concerning said sub net are out of a predetermined range of
allowance defined in said technology information; and

laying out an empty cell including said determined
20 repeater circuit in said I/O area.

8. The design automation method according to claim 7,
wherein said step of determining a repeater circuit includes
the steps of:

performing control in such a way as to execute circuit
25 simulation for a sub net divided by insertion of a selected
repeater circuit to acquire a wiring delay and waveform
depression concerning said divided sub net; and

determining whether said wiring delay and waveform

depression concerning said divided sub net fall within said range of allowance defined in said technology information or not, and searching for an optical repeater circuit by selecting another repeater circuit or further dividing said sub net in case where said wiring delay and waveform depression do not fall within said range of allowance.

5 9. A program for allowing a computer having a memory unit which stores I/O cell layout position information, I/O cell size information, I/O cell test terminal information, technology information including design information, and information on a repeater circuit to be laid out in an empty cell for each type of I/O cells on a chip, which are to be connected to external pins, to execute:

15 a first process of computing a wiring length of a sub net between adjoining I/O cells for test signals (called "test net") to be wired to an area for layout of I/O cells (called "I/O area") at a peripheral portion of a chip by referring to said I/O cell layout position information, I/O cell size information and I/O cell test terminal information in said memory unit and outputting said wiring length;

20 a second process of computing information at least on a wiring resistance and a capacitance for said sub net, causing said circuit simulator to execute circuit simulation to acquire a wiring delay of said sub net and waveform depression at an end of said sub net;

25 a third process of determining an optimal repeater circuit to be inserted in an empty cell where said sub net passes, based on said information on said repeater circuit

stored in said memory unit in case where said wiring delay and waveform depression concerning said sub net are out of a predetermined range of allowance defined in said technology information; and

5 a fourth process of laying out an empty cell including said determined repeater circuit in said I/O area.

10. The program according to claim 9, wherein in said third process, said computer executes:

10 a process of performing control in such a way as to execute circuit simulation for a sub net divided by insertion of a selected repeater circuit to acquire a wiring delay and waveform depression concerning said divided sub net; and

15 a process of determining whether said wiring delay and waveform depression concerning said divided sub net fall within said range of allowance defined in said technology information or not, and searching for an optical repeater circuit by selecting another repeater circuit or further dividing said sub net in case where said wiring delay and
20 waveform depression do not fall within said range of allowance.